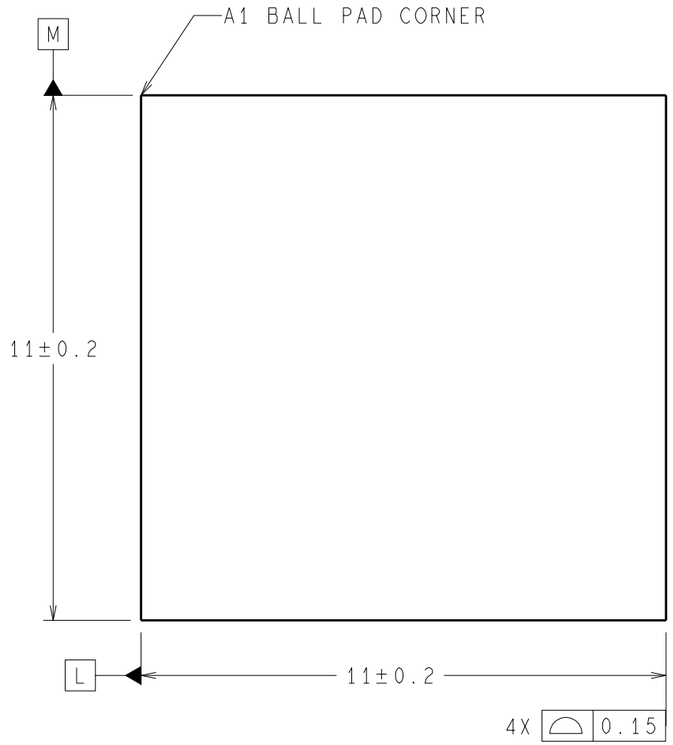
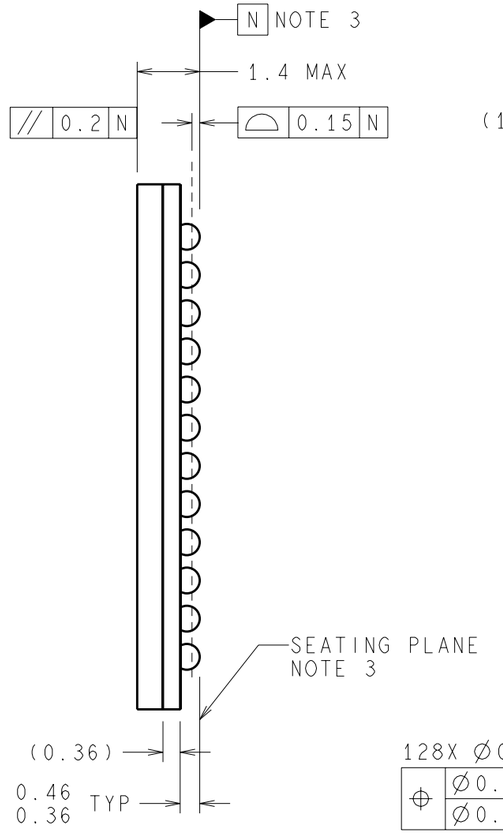
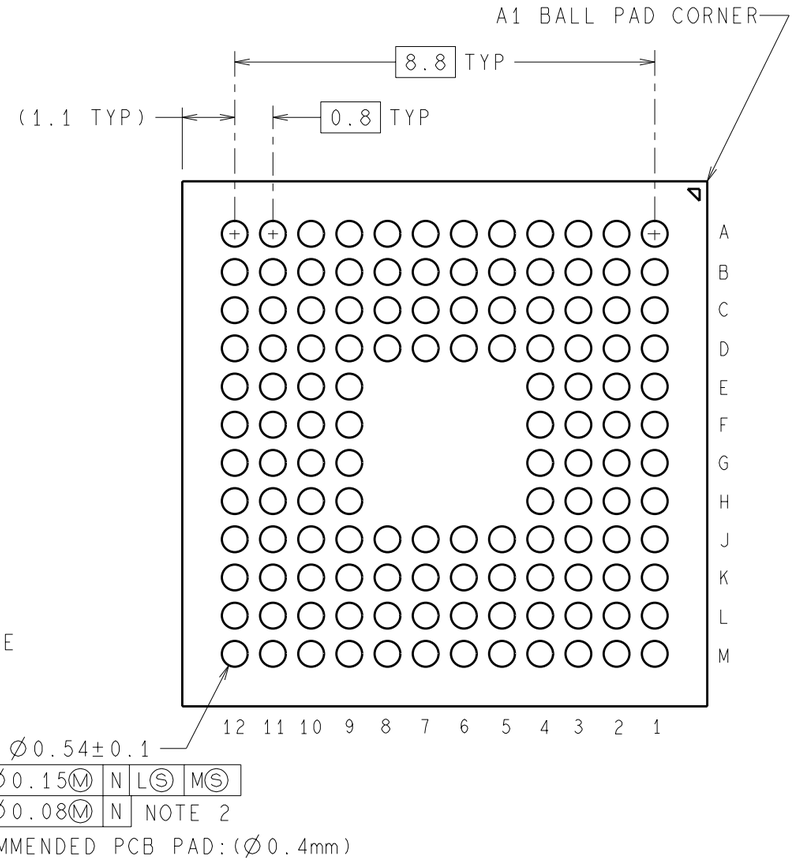
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1954	11/11/2005	TL/RW







NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR SOLDER BALL COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. NO JEDEC REGISTRATION AS OF NOVEMBER 2005.

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN ( ) FOR REFERENCE ONLY

APPROVALS	DATE
DRAWN T LEQUANG	11/11/2005
DFTG. CHK. MARTA SUCHY	11/11/2005
ENGR. CHK. RANDALL WALBERG	11/11/2005

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

FBGA, PLASTIC, LAMINATE,
11x11x1.4mm,
128 BALL, 0.8mm PITCH

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-SLC128B	A

FORMERLY: N/A SHEET 1 of 1